

**LISTING OF CLAIMS**

This listing of claims will replace all prior versions and listings of claims in the application:

Claims 1-10 (Canceled).

Claim 11 (Currently Amended) A method of fabricating a plurality of individual liquid crystal cells, each comprising a first substrate comprising a back electrode and a second active matrix substrate, which are assembled with a sealing frame producing a cavity between the substrates for liquid crystals, ~~the first substrates being formed collectively on a transparent support, the second substrates being formed collectively on a silicon wafer, and comprising contact pads,~~ the method comprising:

collectively forming a plurality of the first substrates on a transparent support;

collectively forming a plurality of the second substrates on a silicon wafer, the second substrates each having contact pads in close proximity to and providing connections to the active matrix circuit;

forming means of for external connection on each first substrate opposite the contact pads of the second substrates ~~to provide external connections;~~

cutting the second substrate from the silicon wafer[[,]] along cutting lines closely adjacent to corresponding to the contour sides of the sealing frame to conserve surface area on the silicon wafer to increase the number of second substrates obtained from the silicon wafer;

~~transferring each of the second cut substrates to the transparent support and assembling each of the second cut substrates on the transparent support[[,]] together with a corresponding first substrate formed on the transparent support and a corresponding~~

sealing frame so that the corresponding sealing frame is disposed between each first and second substrate to form an assembly of a cell, the assembling being further performed to ensure so as to overlap of the contact pads[[],] and by an opposite portion of the means of for external connection[[],] and at least a part of the sealing frame, the at least a part of the sealing frame comprising a seal including an insulating material and conducting elements disposed in the seal for configured to provide electrical continuity between each overlapped contact pad and a corresponding element of the means of for external connection; and separating each assembly into individual liquid crystal cells by cutting the transparent support so that a zone of each first substrate comprising the means of for external connection is overhanging with respect to the second substrate to which it is assembled.

Claim 12 (Currently Amended): ~~the~~ The method of fabrication as claimed in claim 11, further comprising filling the cavities with liquid crystals.

Claim 13 (Previously Presented): The method of fabrication as claimed in claim 11, wherein the conducting elements include conducting balls.

Claim 14 (Previously Presented): The method of fabrication as claimed in claim 11, wherein the conducting elements include resin tags furnished with a conducting layer.

Claim 15 (Previously Presented): The method of fabrication as claimed in claim 11, wherein the conducting elements include metal tags produced on the silicon substrate.

Claim 16 (Previously Presented): The method of fabrication as claimed in claim 11, wherein the conducting elements include spacers.

Claim 17 (Previously Presented): The method of fabrication as claimed in claim 16, wherein other spacer elements are disposed in the seal, the other spacer elements being conducting or otherwise, and of a same nature as or of a different nature from the conducting elements.

Claim 18 (Currently Amended): A liquid crystal cell comprising:  
a first transparent substrate comprising a back electrode and a second silicon substrate comprising an active matrix circuit with contact pads in close proximity to and connected with the active matrix circuit, the substrates being assembled together with a sealing frame producing so as to provide a cavity between the substrates for configured to contain liquid crystals, wherein,  
the second silicon substrate includes a cutout corresponding to a contour of exterior sides that are all closely adjacent to corresponding exterior sides of the sealing frame,  
the cell comprises the transparent substrate includes means of connection of for providing external connections to the active matrix circuit liquid crystal cell that are relocated onto the first substrate and are disposed overhanging with respect to the second silicon substrate with the means for providing the external connections including a portion overlapping with a part of the sealing frame and the contact pads on the silicon substrate, and at least the portion of the sealing frame between the means for providing the external connections and the contact pads includes a seal that overlaps the sealing material containing conducting elements configured to provide electrical continuity between each overlapped contact pad pads on the second substrate and an opposite portion of the means of connection, and conducting elements disposed in the seal for electrical continuity between each of the

~~contact pads and a corresponding portion of the means of connection for providing the external connections.~~

Claim 19 (Currently Amended): The liquid crystal cell as claimed in claim 18, wherein the conducting elements include spacers.

Claim 20 (Currently Amended): The liquid crystal cell as claimed in claim 19, wherein other spacer elements are disposed in the seal, the other spacer elements being conducting or otherwise, and of a same nature as or of a different nature from the conducting elements of the seal.

Claim 21 (Currently Amended): The liquid crystal cell as claimed in claim 18, wherein the conducting elements include conducting balls.

Claim 22 (Currently Amended): The liquid crystal cell as claimed in claim 18, wherein the conducting elements include resin tags furnished with a conducting layer.

Claim 23 (Currently Amended): The liquid crystal cell as claimed in claim 18, wherein the conducting elements include metal tags produced on the silicon substrate.

Claim 24 (Currently Amended): A liquid crystal display comprising:  
a liquid crystal cell,  
wherein the liquid crystal cell comprises a ~~first~~ transparent substrate comprising a back electrode and a ~~second~~ silicon substrate comprising an active matrix circuit with contact pads in close proximity to and connected with the active matrix circuit, the substrates being

assembled together with a sealing frame producing so as to provide a cavity between the substrates for configured to contain liquid crystals,

wherein the second silicon substrate includes a cutout corresponding to a contour of exterior sides that are all closely adjacent to corresponding exterior sides of the sealing frame,

wherein the cell comprises the transparent substrate includes means of connection of for providing external connections to the active matrix circuit liquid crystal cell that are relocated onto the first substrate and are disposed overhanging with respect to the second silicon substrate with the means for providing the external connections including a portion overlapping with a part of the sealing frame and the contact pads on the silicon substrate, and

wherein at least the portion of the sealing frame between the means for providing the external connections and the contact pads includes a seal that overlaps the sealing material containing conducting elements configured to provide electrical continuity between each overlapped contact pad pads on the second substrate and an opposite portion of the means of connection, and conducting elements disposed in the seal for electrical continuity between each of the contact pads and a corresponding portion of the means of connection for providing the external connections.